ABSOCIATION CONNECTING LECTRONICS INDUSTRIES INCOMPACTING	IPC. Bannockt	ourn. Illinois. A	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaratio he declaration en	n of the substan compasses all lo	ces within the manufacture ower level materials for w	rer listed i hich the n	tem. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.	
					rm Type * Declaration Class * stribute Class 6 - RoHS Yes/No, Homogeneous Mate				rials and Mfg Information				
Supplier Information													
Company name* Company u			unique ID			Unique ID Authority				Response Date*			
onsemi										2025-06-04			
Contact Name Title - Contact			ontact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Envir			wiro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repres			esentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product Env			Enviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item	n Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FDMF51	OMF5175 VR14 30A PQFN		45 Power Stage	;	2025-06-04		TH6		58.373	mg	Each	
Manufacturing Proccess Informa	ation							·					
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base		Alloy J	J-STD-020 MSL Rating		Peak Process Body Temperature Max Tim		ature Max Time at Peak	ak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy		1	l		260	С	30	secon	ids 3				
Comments													
evel 1 - maximum time at peak temperat	ture during sol	ldering is 10-3	0 seconds										
for more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	ease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, dmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part nations a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall compass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Supplier may nave relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not dependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ruffication in this paragraph. If the Company and the Supplier rint oa written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of at agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written									
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.899	mg	Supplier	Zinc (Zn)	7440-66-6		0.0023	mg
			Supplier	Iron (Fe)	7439-89-6		0.0456	mg
			Supplier	Copper (Cu)	7440-50-8		1.8496	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0015	mg
Die	1.093	mg	Supplier	Silicon (Si)	7440-21-3		1.093	mg
Die Attach Solder	2.402	mg	Supplier	Silver (Ag)	7440-22-4		0.06	mg
			А	Lead (Pb)	7439-92-1	7a	2.2218	mg
			Supplier	Tin (Sn)	7440-31-5		0.1201	mg
Lead Frame	21.247	mg	Supplier	Silver (Ag)	7440-22-4		1.0624	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0255	mg
			Supplier	Iron (Fe)	7439-89-6		0.5099	mg
			Supplier	Copper (Cu)	7440-50-8		19.6322	mg
			Supplier	Phosphorus (P)	7723-14-0		0.017	mg
Mold Compound-Black	30.0	mg		Epoxy resin	proprietary data		3.99	mg
			Supplier	Carbon Black (C)	1333-86-4		0.06	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.95	mg
Plating	1.589	mg	Supplier	Tin (Sn)	7440-31-5		1.589	mg
Wire Bond - Cu	0.143	mg	Supplier	Palladium (Pd)	7440-05-3		0.0026	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.1403	mg